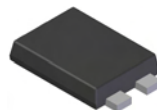


Features

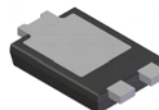
- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Forward Voltage Drop
- Very Low Leakage Current
- High Forward Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

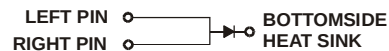
- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ③
- Polarity: See Diagram
- Weight: 0.096 grams (approximate)



Top View



Bottom View



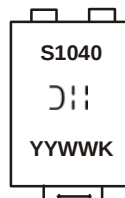
Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 2)

Part Number	Case	Packaging
PDS1040-13	Power DI [®] 5	5000/Tape & Reel

Notes: 1. EU Directive **2002/95/EC** (RoHS). All applicable RoHS exemptions applied, see *EU Directive 2002/95/EC Annex Notes*.
 2. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



S1040 = Product type marking code
 311 = Manufacturers' code marking
 YYWW = Date code marking
 YY = Last two digits of year (ex: 04 for 2004)
 WW = Week code (01 - 53)
 K = Factory designator

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Rectified Output Current (see also Figure 5)	I _O	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	275	A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	R _{θJS}	—	1.5	°C/W
Thermal Resistance Junction to Ambient Air (Note 3)	R _{θJA}	95	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 4)	R _{θJA}	75	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	50	—	°C/W
Operating Junction Temperature Range V _R ≤ 80% V _{RRM} V _R ≤ 50% V _{RRM}	T _J	-65 to +150 -65 to +180		°C
Storage Temperature Range	T _{STG}	-65 to +150		°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	40	—	—	V	I _R = 1mA
Forward Voltage	V _F	—	0.45	0.49	V	I _F = 8A, T _S = 25°C
		—	0.47	0.51		I _F = 10A, T _S = 25°C
		—	—	0.41		I _F = 8A, T _S = 125°C
		—	0.42	0.49		I _F = 10A, T _S = 125°C
Reverse Leakage Current (Note 6)	I _R	—	0.02	0.3	mA	T _S = 25°C, V _R = 35V
		—	5.5	25		T _S = 100°C, V _R = 35V
		—	0.03	0.7		T _S = 25°C, V _R = 40V
		—	6.5	50		T _S = 100°C, V _R = 40V

- Notes:
- FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 - Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 - Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
 - Short duration pulse test used to minimize self-heating effect.
 - Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 3.0mm.
 - Devices mounted such that R_{θJA} = 19°C/W.

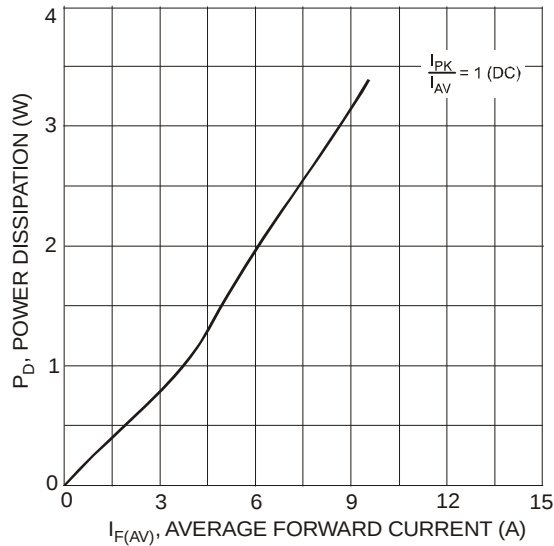


Fig. 1 Forward Power Dissipation

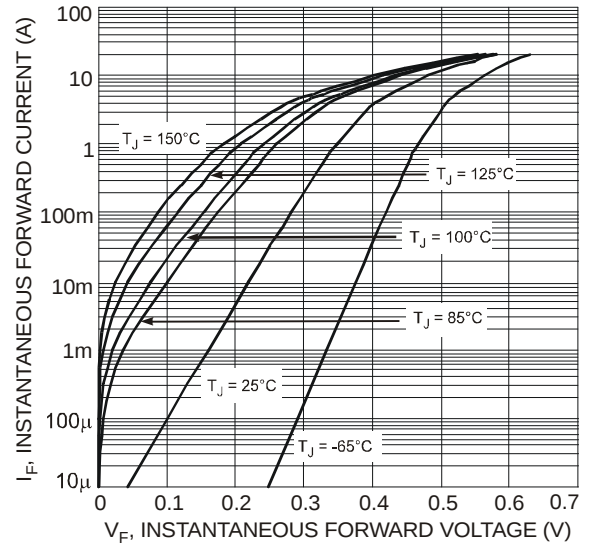


Fig. 2 Typical Forward Characteristics

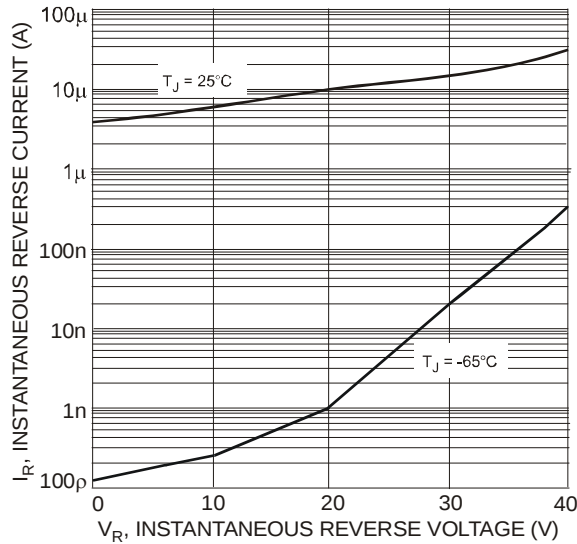


Fig. 3 Typical Reverse Characteristics

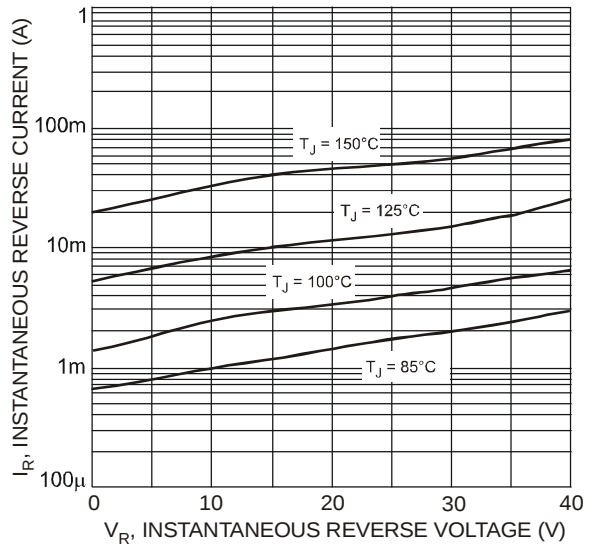


Fig. 4 Typical Reverse Characteristics

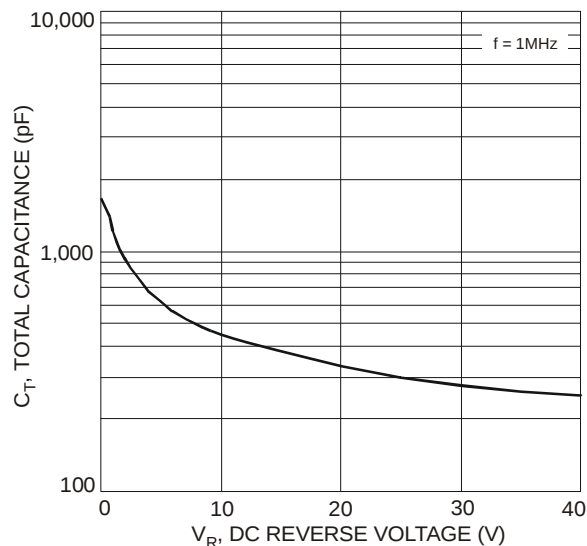


Fig. 5 Total Capacitance vs. Reverse Voltage

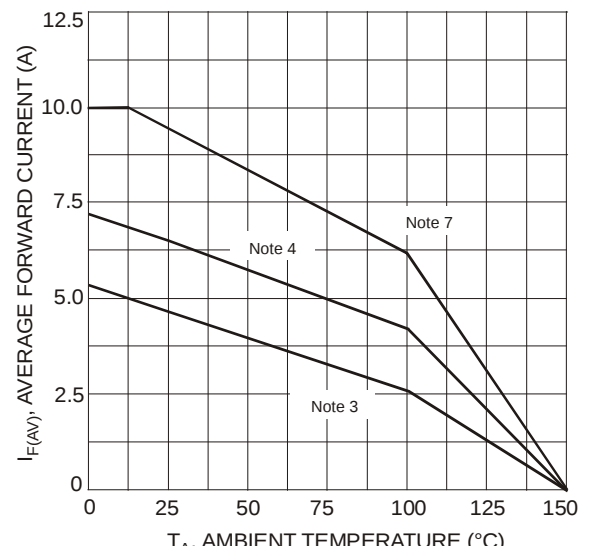
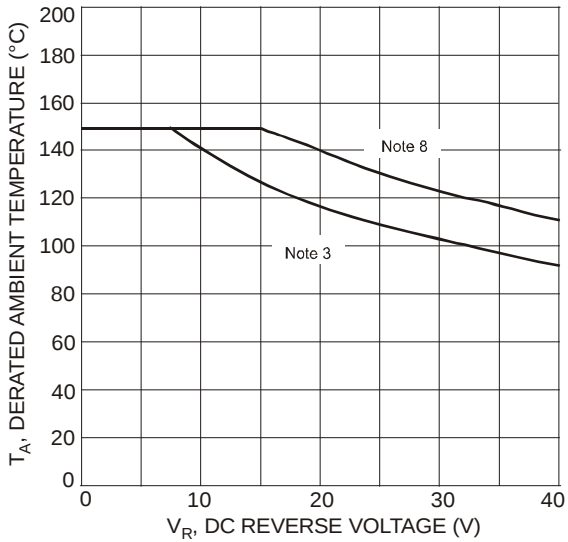
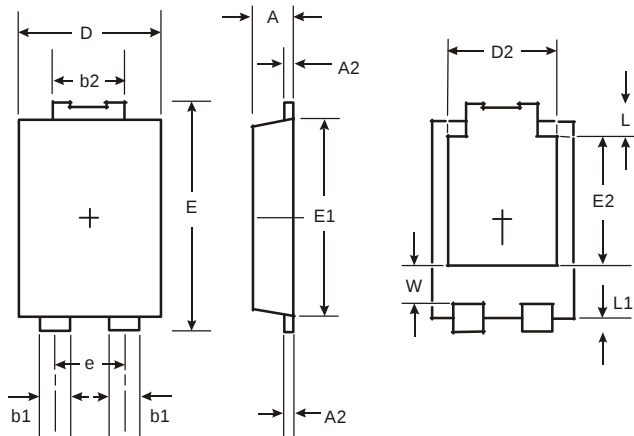


Fig. 6 Forward Current Derating Curve

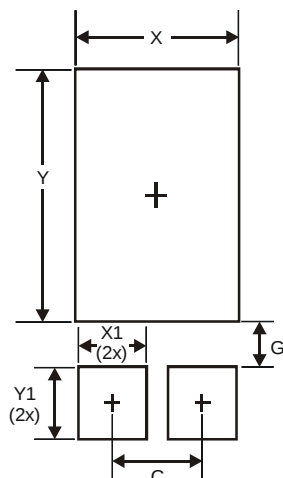


Package Outline Dimensions



PowerDI [®] 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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PDS1040

Document number: DS30538 Rev. 9 - 2

4 of 5

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November 2010
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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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